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[MOSFET](#) - Power, N-Channel, SUPERFET$^{®}$ III, FAST

650 V, 190 mΩ, 16 A

NTPF190N65S3H

Description

SUPERFET III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provides superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III FAST MOSFET series helps minimize various power systems and improve system efficiency.

Features

- 700 V @ T_J = 150°C
- Typ. $R_{DS(on)}$ = 156 mΩ
- Ultra Low Gate Charge (Typ. Q_g = 31 nC)
- Low Effective Output Capacitance (Typ. $C_{oss(eff.)}$ = 292 pF)
- 100% Avalanche Tested
- These Devices are Pb−Free and are RoHS Compliant

Applications

- Computing / Display Power Supplies
- Telecom / Server Power Supplies
- Industrial Power Supplies
- Lighting / Charger / Adapter

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V_{DSS}	$R_{DS(ON)}$ MAX	I_D MAX
650 V	190 mΩ @ 10 V	16 A
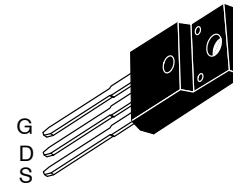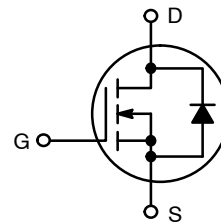
TO−220 FULLPAK
CASE 221D

MARKING DIAGRAM


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T190N
65S3H
AYWWZZ
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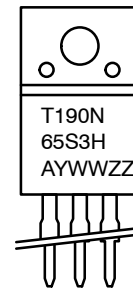
T190N65S3H = Specific Device Code
A   = Assembly Location
Y   = Year
WW   = Work Week
ZZ   = Lot Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

December, 2020 − Rev. 0

Publication Order Number:
NTPF190N65S3H/D

NTPF190N65S3H

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C, Unless otherwise specified)

Symbol	Parameter		Value	Unit
V_{DSS}	Drain to Source Voltage		650	V
V_{GSS}	Gate to Source Voltage	DC	±30	V
		AC (f > 1 Hz)	±30	V
I_D	Drain Current	Continuous (T_C = 25°C)	16*	A
		Continuous (T_C = 100°C)	10*	
I_{DM}	Drain Current	Pulsed (Note 1)	45*	A
E_{AS}	Single Pulsed Avalanche Energy (Note 2)		142	mJ
I_{AS}	Avalanche Current (Note 2)		3.6	A
E_{AR}	Repetitive Avalanche Energy (Note 1)		1.29	mJ
dv/dt	MOSFET dv/dt		120	V/ns
	Peak Diode Recovery dv/dt (Note 3)		20	
P_D	Power Dissipation	(T_C = 25°C)	32	W
		Derate Above 25°C	0.25	W/°C
T_J, T_{STG}	Operating and Storage Temperature Range		−55 to +150	°C
T_L	Maximum Lead Temperature for Soldering, 1/8″ from Case for 5 s		260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
*Drain current limited by maximum junction temperature.
1. Repetitive rating: pulse-width limited by maximum junction temperature.
2. I_{AS} = 3.6 A, R_G = 25 Ω, starting T_J = 25°C.
3. $I_{SD} \leq$ 8 A, di/dt $\leq$ 200 A/μs, $V_{DD} \leq$ 400 V, starting T_J = 25°C.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	3.88	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Shipping
NTPF190N65S3H	T190N65S3H	TO−220 FULLPAK	50 Units / Tube

NTPF190N65S3H

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
BV_{DSS}	Drain to Source Breakdown Voltage	V_{GS} = 0 V, I_D = 1 mA, T_J = 25°C	650			V
		V_{GS} = 0 V, I_D = 1 mA, T_J = 150°C	700			V
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temperature Coefficient	I_D = 10 mA, Referenced to 25°C		0.63		V/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 650 V, V_{GS} = 0 V			1	μA
		V_{DS} = 520 V, T_C = 125°C		0.8		
I_{GSS}	Gate to Body Leakage Current	V_{GS} = ±30 V, V_{DS} = 0 V			±100	nA
ON CHARACTERISTICS						
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS} = V_{DS}, I_D = 1.4 mA	2.4		4.0	V
$R_{DS(on)}$	Static Drain to Source On Resistance	V_{GS} = 10 V, I_D = 8 A		156	190	mΩ
g_{FS}	Forward Transconductance	V_{DS} = 20 V, I_D = 8 A		18		S
DYNAMIC CHARACTERISTICS						
C_{iss}	Input Capacitance	V_{DS} = 400 V, V_{GS} = 0 V, f = 250 kHz		1600		pF
C_{oss}	Output Capacitance			23		pF
$C_{oss(eff.)}$	Effective Output Capacitance	V_{DS} = 0 V to 400 V, V_{GS} = 0 V		292		pF
$C_{oss(er.)}$	Energy Related Output Capacitance	V_{DS} = 0 V to 400 V, V_{GS} = 0 V		41		pF
$Q_{g(tot)}$	Total Gate Charge at 10 V	V_{DS} = 400 V, I_D = 8 A, V_{GS} = 10 V (Note 4)		31		nC
Q_{gs}	Gate to Source Gate Charge			7.1		nC
Q_{gd}	Gate to Drain "Miller" Charge			7.9		nC
ESR	Equivalent Series Resistance	f = 1 MHz		1.1		Ω
SWITCHING CHARACTERISTICS						
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = 400 V, I_D = 8 A, V_{GS} = 10 V, R_g = 10 Ω (Note 4)		19		ns
t_r	Turn-On Rise Time			7.8		ns
$t_{d(off)}$	Turn-Off Delay Time			61		ns
t_f	Turn-Off Fall Time			3.5		ns
SOURCE-DRAIN DIODE CHARACTERISTICS						
I_S	Maximum Continuous Source to Drain Diode Forward Current				16	A
I_{SM}	Maximum Pulsed Source to Drain Diode Forward Current				45	A
V_{SD}	Source to Drain Diode Forward Voltage	V_{GS} = 0 V, I_{SD} = 8 A			1.2	V
t_{rr}	Reverse Recovery Time	V_{DD} = 400 V, I_{SD} = 8 A, dI_F/dt = 100 A/μs		259		ns
Q_{rr}	Reverse Recovery Charge			3.2		μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
4. Essentially independent of operating temperature typical characteristics.

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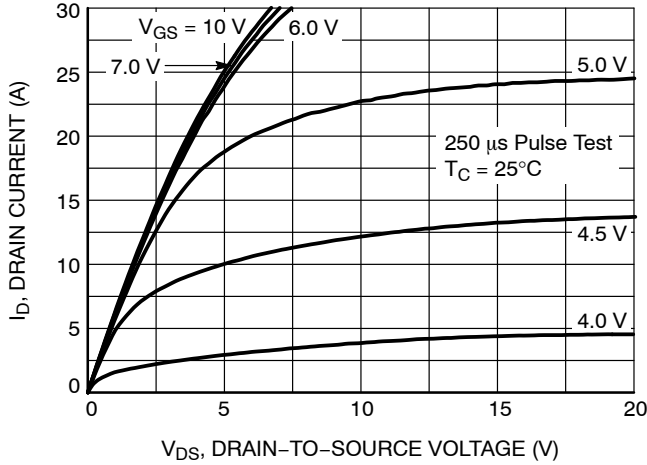
TYPICAL CHARACTERISTICS
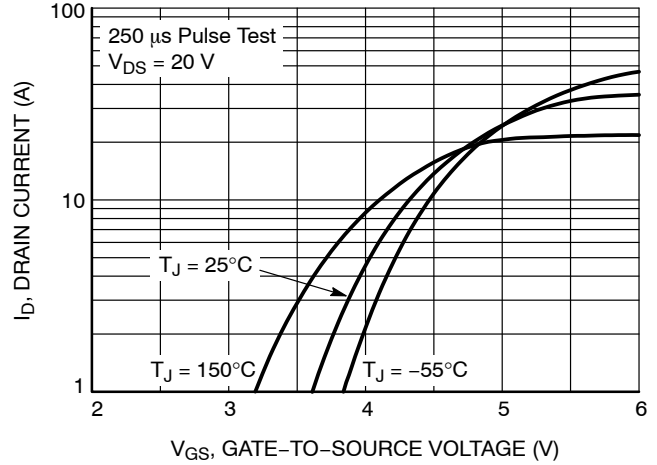

Figure 1. On–Region Characteristics
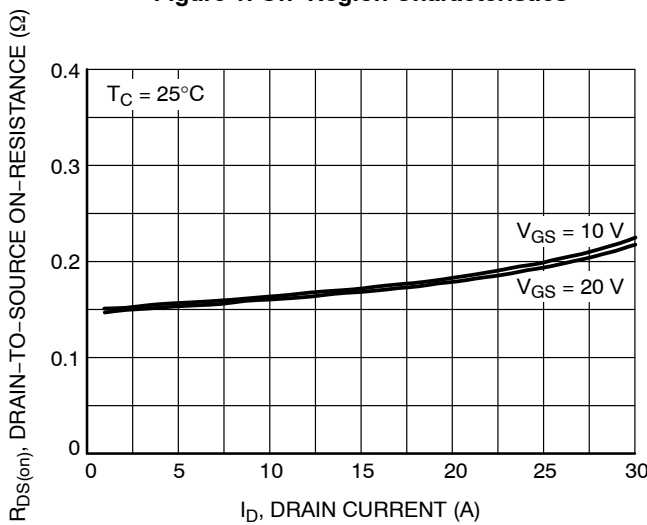

Figure 2. Transfer Characteristics

Figure 3. On Resistance Variation vs. Drain Current and Gate Voltage
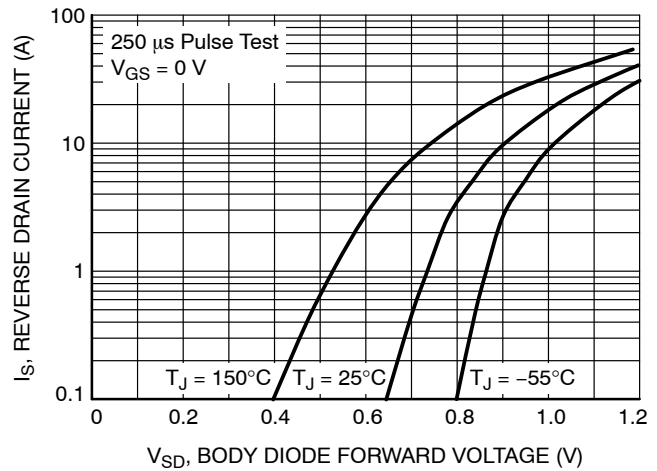

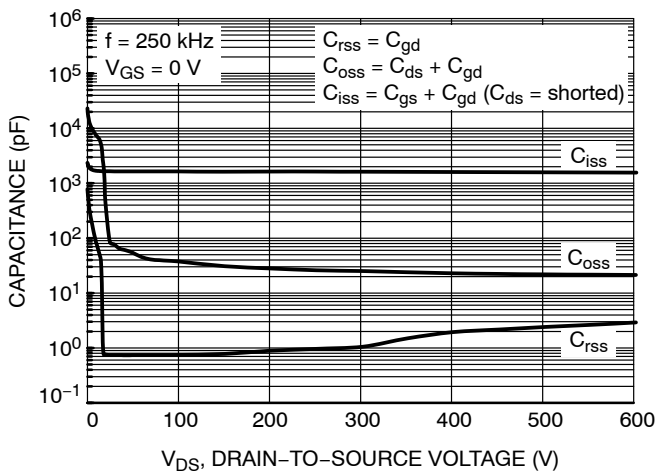Figure 4. Diode Forward Voltage Variation vs. Source Current and Temperature

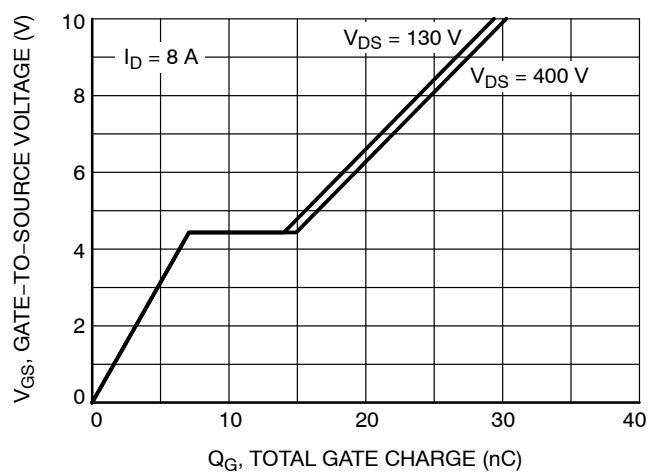Figure 5. Capacitance Characteristics

Figure 6. Gate Charge Characteristics
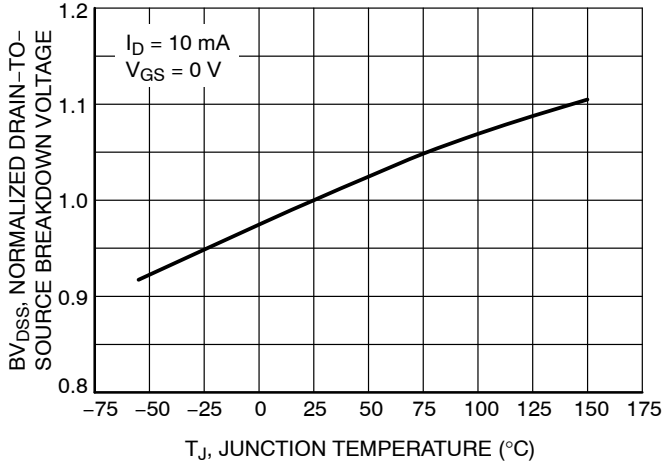
NTPF190N65S3H

TYPICAL CHARACTERISTICS

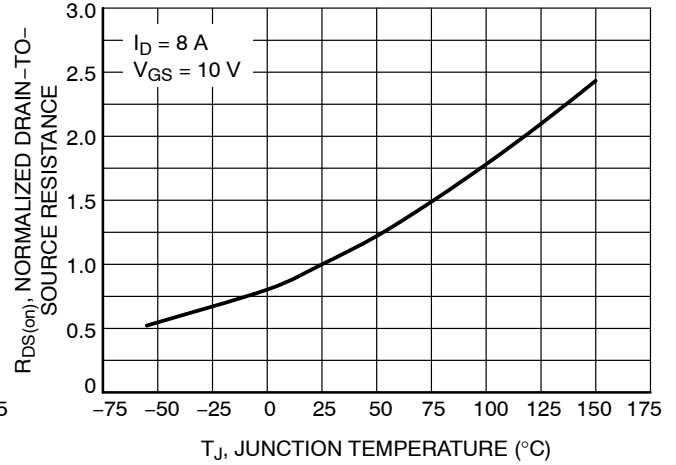

Figure 7. Breakdown Voltage Variation vs. Temperature
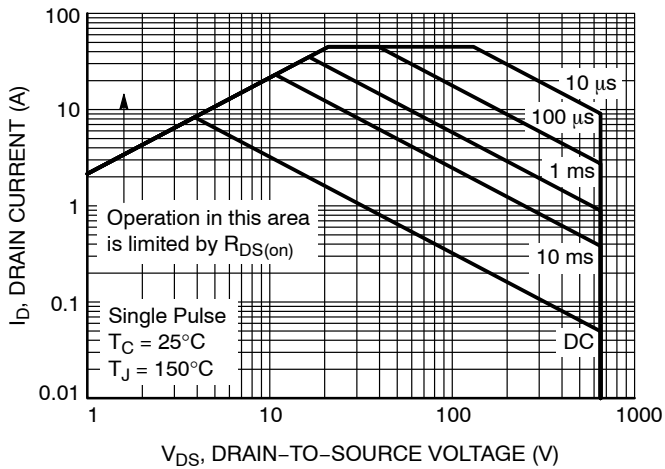

Figure 8. On−Resistance Variation vs. Temperature

Figure 9. Maximum Safe Operating Area
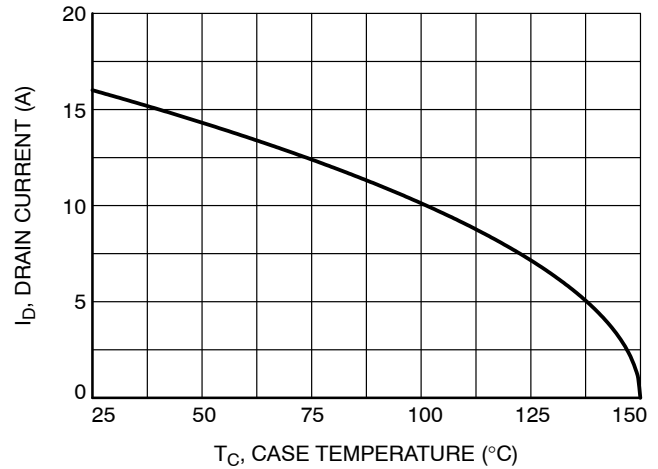
Figure 10. Maximum Drain Current vs. Case Temperature
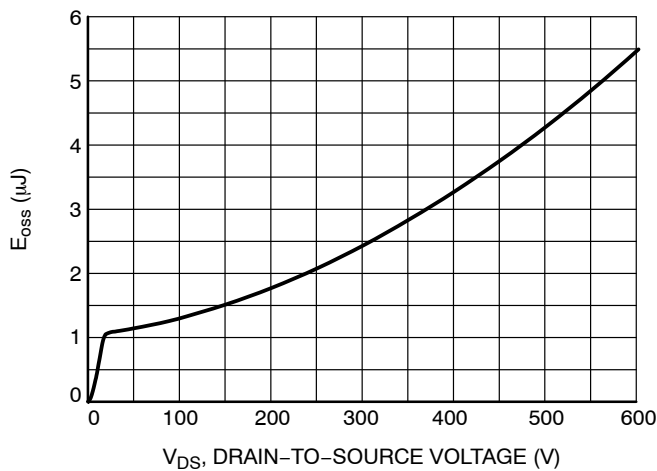
Figure 11. E$_{oss}$ vs. Drain−to−Source Voltage

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TYPICAL CHARACTERISTICS
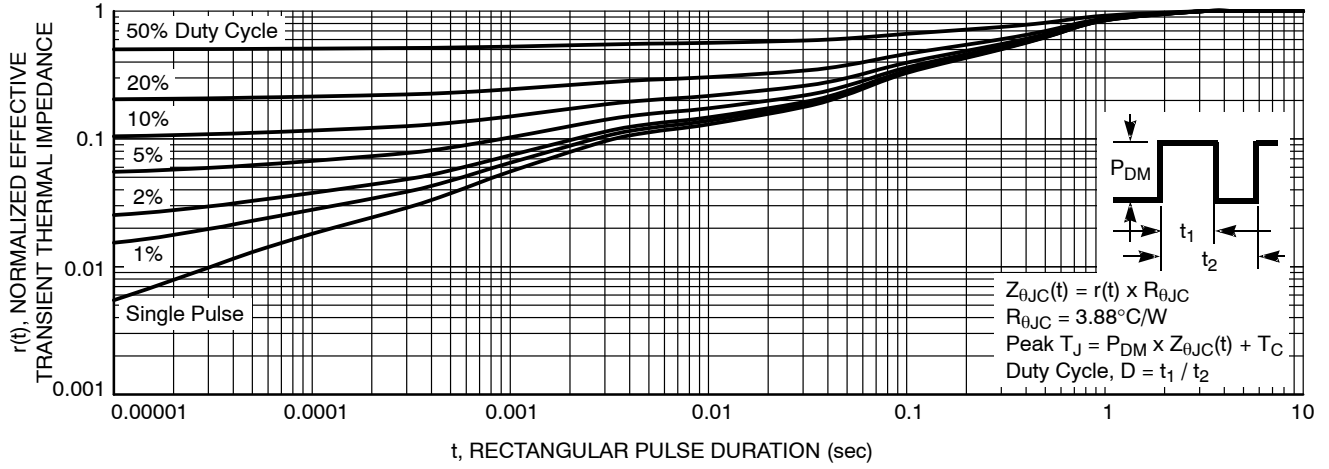
Figure 12. Transient Thermal Response Curve
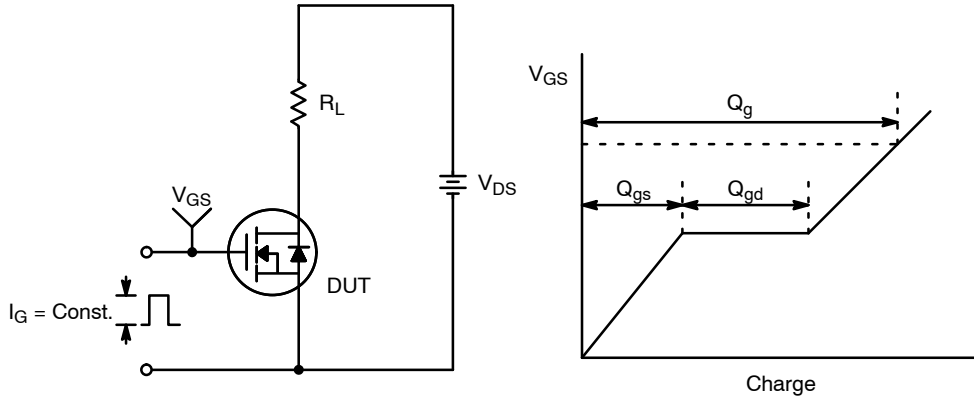
Figure 13. Gate Charge Test Circuit & Waveform
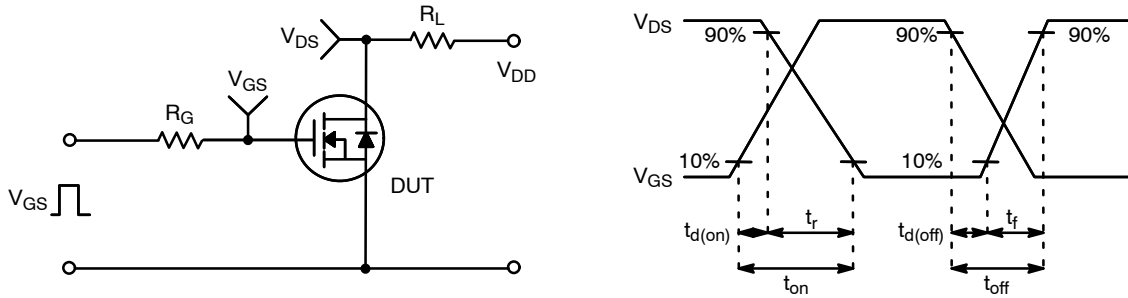
Figure 14. Resistive Switching Test Circuit & Waveforms

$$E_{AS} = \frac{1}{2} \cdot L I_{AS}{}^2$$
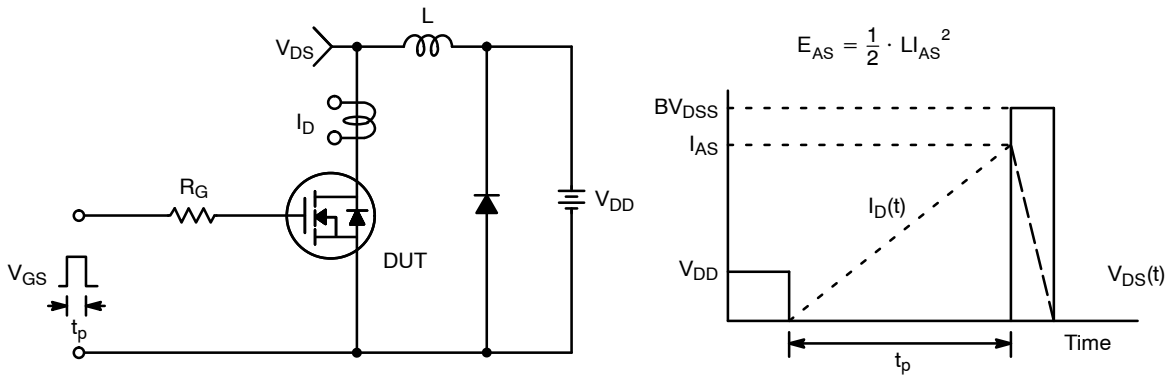
Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms
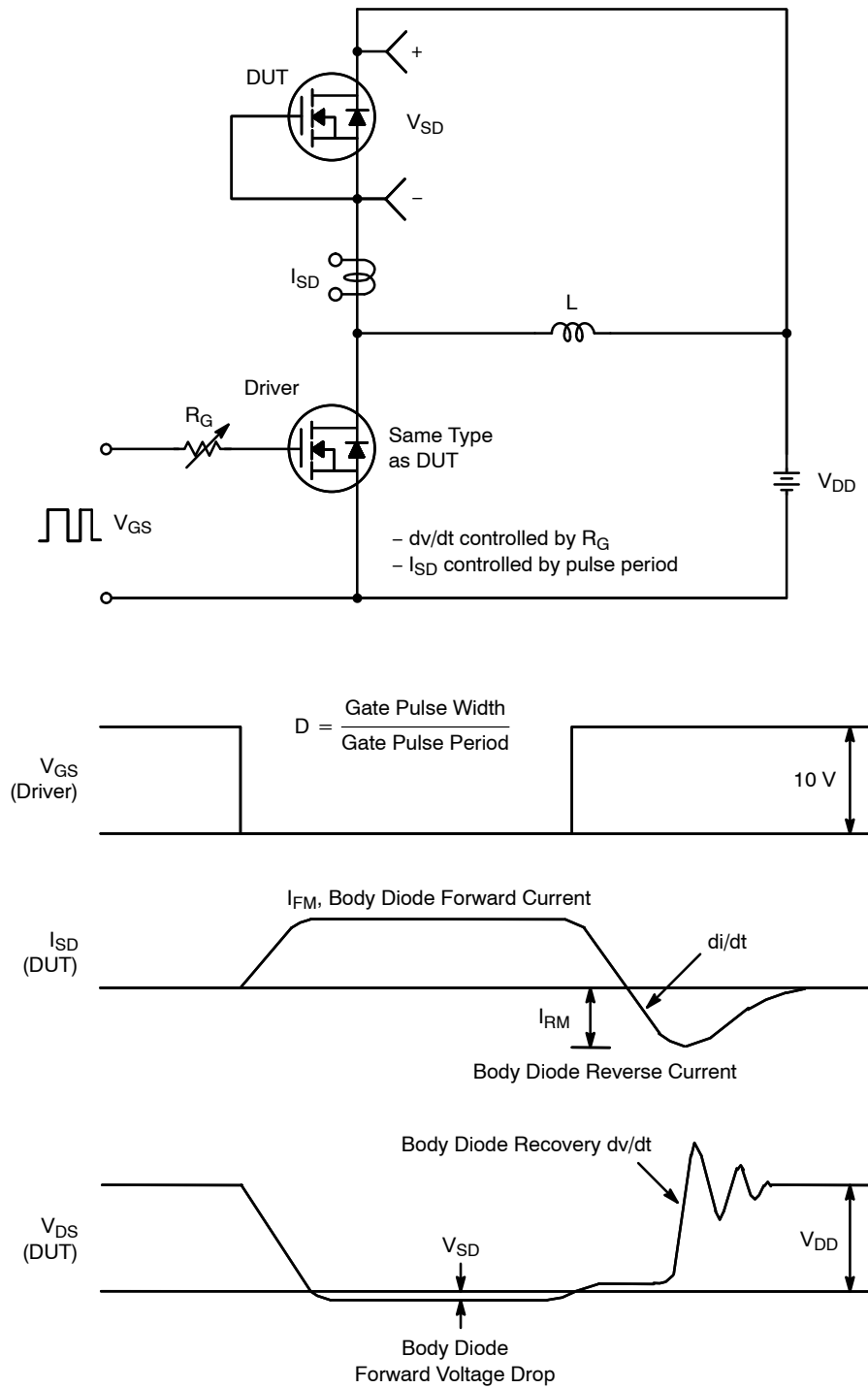
Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

PACKAGE DIMENSIONS

TO−220 FULLPAK
CASE 221D−03
ISSUE K
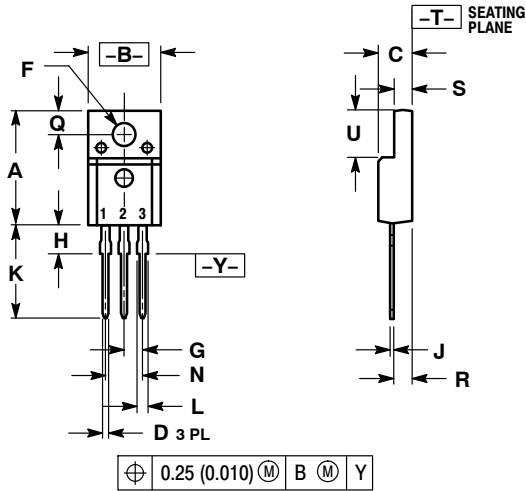
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH
3. 221D−01 THRU 221D−02 OBSOLETE, NEW STANDARD 221D−03.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.617	0.635	15.67	16.12
B	0.392	0.419	9.96	10.63
C	0.177	0.193	4.50	4.90
D	0.024	0.039	0.60	1.00
F	0.116	0.129	2.95	3.28
G	0.100 BSC		2.54 BSC	
H	0.118	0.135	3.00	3.43
J	0.018	0.025	0.45	0.63
K	0.503	0.541	12.78	13.73
L	0.048	0.058	1.23	1.47
N	0.200 BSC		5.08 BSC	
Q	0.122	0.138	3.10	3.50
R	0.099	0.117	2.51	2.96
S	0.092	0.113	2.34	2.87
U	0.239	0.271	6.06	6.88

◊